

项目ITEMS	参数/PARAMETERS		
	单面板/SINGLE-SIDED	双面板/DOUBLE-SIDED	多层板/MULTI-LAYER
层数/LAYERS	1	2	6~8
铝箔厚度/COPPER THICKNESS (um)	17-70	17-70	17-70
基板厚度/MATERIAL THICKNESS (mm)	0.8-3.2	0.8-3.2mm	0.35-3.2mm
最小板厚/MIN. BOARD THICKNESS (mm)	0.8	0.8	>=4 Layer : 0.4
			6 Layer: 0.8
最小线宽/MIN. LINE WIDTH (mm)	0.12	0.1	0.1
最小线距/MIN. LINE SPACE (mm)	0.12	0.1	0.1
最小焊环/MIN. ANNUL RING	内层INNER	-	≥0.05um
	外层OUTER	≥0.2mm	≥0.076mm
最小孔径/MIN.HOLE SIZE	冲孔PUNCH	0.7mm	
	钻孔CNC DRILL	0.3mm	0.15
成品孔径公差/HOLE DIAMETER TOLERANCE OF FINAL PRODUCTS (mm)	模具冲板/Punch :±0.1	P.T.H.: ±0.076	P.T.H.: ±0.076
	电脑钻孔/CNC Drilling :±0.076	Non-P.T.H. :±0.05	Non-P.T.H. :±0.05
孔壁铜厚/HOLE WALL COPPER THICKNESS	-	≥20um	≥25.4um
成品板面积/MAX. BOARD SIZE	400 x 500mm	560 x 600mm	560 x 600mm
成型公差/OUTLINE TOLERANCE (mm)	模具冲板/Pouched :±0.5 - 1.0	模具冲板/Pouched :±0.1	模具冲板/Pouched :±0.1
	电脑锣板/CNC Routing :±0.15	电脑锣板/CNC Routing :±0.15	电脑锣板/CNC Routing :±0.15
抗剥离强度/PEEL STRENGTH	10.4n/cm	12.3n/cm	12.3n/cm
翘曲度/WARP AND TWIST	≤1.5%	≤1.0%	≤1.0%
绝缘电阻/INSULATION RESISTER	≥5mΩ	≥5mΩ	≥5mΩ
测试电压/TEST VOLTAGE	50-100DCV	100DCV	100-200DCV
阻焊硬度/SOLDER MASK HARDNESS	6H	6H	6H
阻焊耐焊性/SOLDER ABILITY	245°C 5秒	245°C 10秒	245°C 10秒
热冲击能力/HOT IMMERSION ABILITY	260°C 10秒	288°C 5秒	288°C 5秒
表面处理/SURFACE TREATMENT	OSP, HASL(Lead Free), Gold Finger, Carbon Paste, Silver Paste, Immersion Gold		
板材类型/ANSI GRADE	XPC,FR1,CEM-1,CEM-3,FR-4	FR-4、CEM-1、CEM-3	FR-4
UL阻燃级别/UL FLAME RATING	94HB - 94V-0	94V-0	94V-0
质量标准/QUALITY STANDARD	IPC-A-600F	IPC-A-600F,IPC-ML-950	IPC-A-600F,IPC-ML-950